

ABSTRACT OF THE DISCLOSURE

A silicone-epoxy resin is mixed with a conductivity enhancing agent, such as carbon black, and is cured to control the resistivity of films that may be used as mold release agents in mold processing or mold shaping electrically sensitive energetic compositions, such as rocket fuels, explosives, gas generator fuels and the like. The uncured precursor to the mold release agent is placed as a coating on molds that are used in these processes. Upon curing on the mold, the enhanced conductivity of the film permits dissipation of static electricity from the electrically sensitive energetic compositions.

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